SN74AHC1G02-EP SINGLE 2-INPUT POSITIVE-NOR GATE

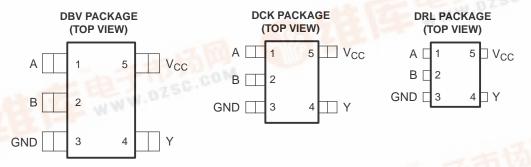
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#### **FEATURES**

- Controlled Baseline
  - One Assembly Site
  - One Test Site
  - One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree (1)
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Operating Range of 2 V to 5.5 V
- Max t<sub>pd</sub> of 8.5 ns at 5 V
- Low Power Consumption, 10 μA Max I<sub>CC</sub>
- ±8 mA Output Drive at 5 V
- Schmitt Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

#### DESCRIPTION/ORDERING INFORMATION

This device contains a single 2-input NOR gate that performs the Boolean function  $Y = \overline{A} \bullet \overline{B}$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

#### ORDERING INFORMATION(1)

TA	PACKAG	E <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	SOT (SC-70) - DCK	Reel of 3000	SN74AHC1G02MDCKREP	CGC

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI
website at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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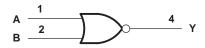
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#### **FUNCTION TABLE**

INP	UTS	OUTPUT
Α	В	Υ
Н	Х	L
X	Н	L
L	L	Н

#### **LOGIC DIAGRAM (POSITIVE LOGIC)**



#### Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	7	V	
VI	Input voltage range <sup>(2)</sup>		-0.5	7	V
Vo	Output voltage range <sup>(2)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-20	mA
$I_{OK}$	Output clamp current	$V_O < 0$ or $V_O = 0$ to $V_{CC}$		±20	mA
Io	Continuous output current	$V_O = 0$ to $V_{CC}$		±25	mA
	Continuous current through V <sub>CC</sub> or GND	V <sub>CC</sub> or GND		±50	mA
$\theta_{JA}$	Package thermal impedance (3)	DCK package		252	°C/W
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed. The package thermal impedance is calculated in accordance with JESD 51-7.

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#### <del>宣阅 NY4//HO1602 EP 1//////H</del>

### Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage		2	5.5	V	
		V <sub>CC</sub> = 2 V	1.5			
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		V	
		V <sub>CC</sub> = 5.5 V	3.85			
		V <sub>CC</sub> = 2 V		0.5		
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9	V	
		V <sub>CC</sub> = 5.5 V		1.65		
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	V <sub>CC</sub>	V	
		V <sub>CC</sub> = 2 V		-50	μΑ	
I <sub>OH</sub>	High-Level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3$		-4	Λ	
		$V_{CC} = 5 \text{ V} \pm 0.5$		-8	mA	
		V <sub>CC</sub> = 2 V		50	μΑ	
I <sub>OL</sub>	Low-Level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3$		4		
		$V_{CC} = 5 V \pm 0.5$		8		
Λ+/Λ.,	Innut transition vias or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100	2011	
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		20	ns/V	
T <sub>A</sub>	Operating free-air temperature		-55	125	°C	

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

#### SN74AHC1G02-EP SINGLE 2-INPUT POSITIVE-NOR GATE





#### **Electrical Characteristics**

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V	TA	= 25°C		T <sub>A</sub> = -55°C TC	125°C	UNIT	
PARAMETER	1EST CONDITIONS	V <sub>cc</sub>	MIN	TYP	MAX	MIN	MAX	UNIT	
		2 V	1.9	2		1.9			
	$I_{OH} = -50 \mu A$	3 V	2.9	3		2.9			
V <sub>OH</sub>		4.5 V	4.4	4.5		4.4		V	
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48			
	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8			
	I <sub>OL</sub> = 50 μA	2 V			0.1		0.1		
		3 V			0.1		0.1		
V <sub>OL</sub>		4.5 V			0.1		0.1	V	
	$I_{OL} = 4 \text{ mA}$	3 V			0.36		0.44		
	$I_{OL} = 8 \text{ mA}$	4.5 V			0.36		0.44		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ	
I <sub>cc</sub>	$V_I = V_{CC}$ or GND, $O = 0$	5.5 V			1		10	μΑ	
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		4	10		10	pF	

#### **Switching Characteristics**

over operating free-air temperature range,  $V_{CC} = 3.3 \pm 0.3 \text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	չ = 25°C		T <sub>A</sub> = -55°C T	O 125°C	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNII
t <sub>PLH</sub>	A or P	V	C _ 50 pE		8.1	11.4	1	13	20
t <sub>PHL</sub>	A or B	r	$C_L = 50 \text{ pF}$		8.1	11.4	1	13	ns

#### **Switching Characteristics**

over operating free-air temperature range,  $V_{CC} = 5 \pm 0.5 \text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	λ = 25°C		T <sub>A</sub> = -55°C	ΓΟ 125°C	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNII
t <sub>PLH</sub>	A or D	V	C		5.1	7.5	1	8.5	20
t <sub>PHL</sub>	A or B	r	$C_L = 50 \text{ pF}$		5.1	7.5	1	8.5	ns

#### **Operating Characteristics**

 $V_{CC}$  = 5 V,  $T_A$  = 25°C

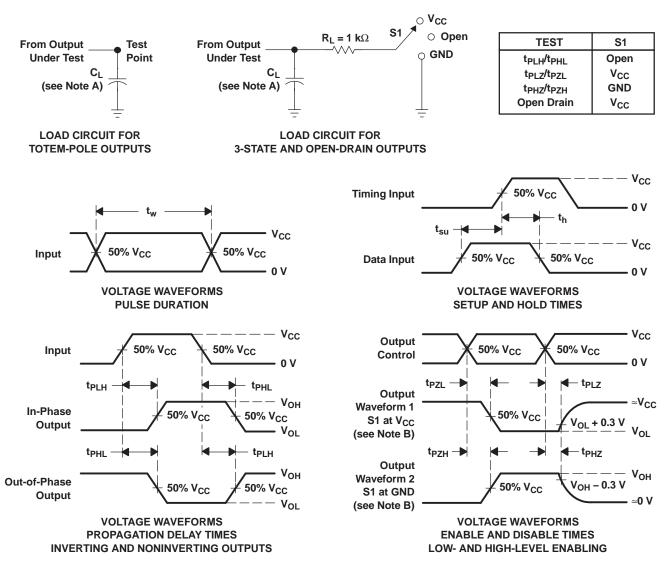
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load, f = 1 MHz	15	pF

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RUMENTS

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

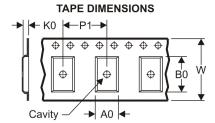
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq$  3 ns,  $t_f \leq$  3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

13-Mar-2008

#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

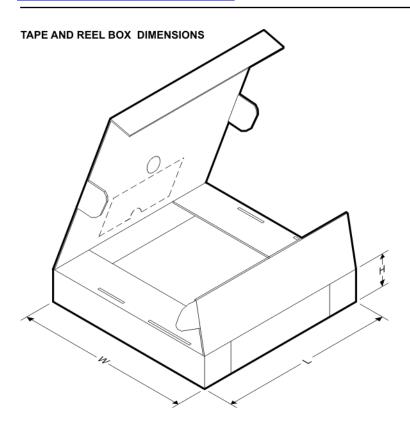
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC1G02MDCKRE P	SC70	DCK	5	3000	180.0	9.2	4.0	2.24	2.34	4.0	8.0	Q3

13-Mar-2008

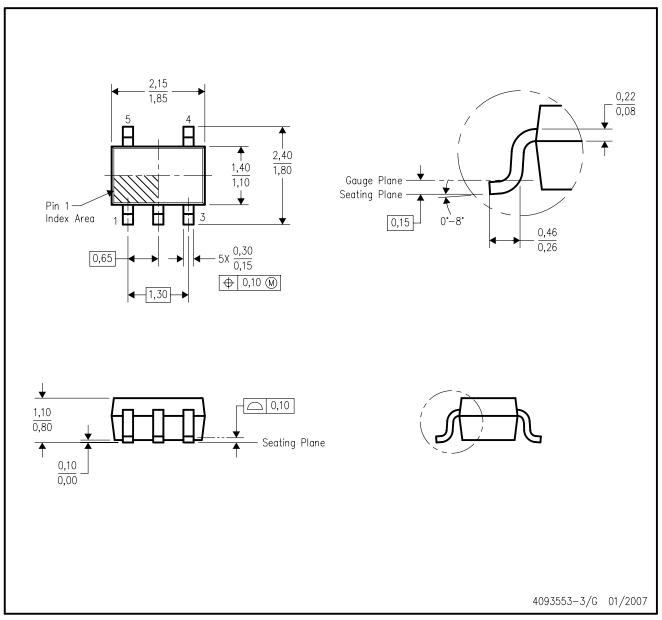


#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC1G02MDCKREP	SC70	DCK	5	3000	202.0	201.0	28.0

## DCK (R-PDSO-G5)

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



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